**Abstract**

The specification describes techniques for applying solder bumps to IC chips. The solder bump sites are first provided with under bump metallization (UBM) for solder bump interconnections to the Al bonding sites on the IC chip. The substrate, i.e. the capping layer of the IC chip, is coated with photoresist and patterned to expose the UBM and a peripheral portion of the capping layer around the UBM. The solder paste is then applied and reflowed to form the solder bump. Since the photoresist hardens and becomes difficult to remove after the reflow step, a sacrificial buffer layer is interposed between the photoresist and the capping layer to facilitate removal of the photoresist without attacking the IC chip surface.

This Sheet Has Been Replaced

